

2018 IEEE International **Ultrasonics Symposium**



(Including Short Courses & Tutorials)

October 22-25, 2018 Portopia Hotel, Kobe, Japan

Sponsored by the IEEE Ultrasonics, Ferroelectrics, & Frequency Control Society

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First Call for Papers

Abstract deadline: May 4, 2018

Abstract submission and conference website: http://sites.ieee.org/ius-2018/

The annual 2018 IEEE International Ultrasonics Symposium (IUS) will be held at the Portopia Hotel, Kobe, Japan, from October 22-25, 2018. The Portopia Hotel is located on Port Island, the first man-made island of Kobe. Access to Port Island is easy because the Kansai International Airport (KIX) is directly connected by a High Speed Ferry (Bay Shuttle).

The abstracts should be submitted in electronic form according to the specific information posted on the conference web page. Each abstract will receive careful review and evaluation by the Symposium Technical Program Committee. Evaluation criteria will include originality of the work, contribution to the state-of-the-art, and overall interest to the ultrasonics community. Papers are solicited for this conference describing original work in the field of ultrasonics from the following subject classifications:

Group 1: Medical Ultrasonics

MBB Medical Beamforming and Beam Steering

MBE Biological Effects & Dosimetry

MBF Blood Flow Measurement

MCA Contrast Agents

MEL Elastography

MIM Medical Imaging

MPA Medical Photoacoustics

MSD System & Device Design

MSP Medical Signal Processing

MTC Medical Tissue Characterization

MTH Therapeutics, Hyperthermia, and Surgery

Group 2: Sensors, NDE & Industrial Applications

NAF Acoustic Microfluidics

NAI Acoustic Imaging

NAM Acoustic Microscopy

NAS Acoustic Sensors

NDE General NDE Methods

NEH Energy Harvesting

NFM Flow Measurement

NMC Material & Defect Characterization

NPA Photoacoustics

NPC Process Control

NSP Signal Processing NTD Transducers: NDE and Industrial

NUA Underwater Acoustics

NWP Wave Propagation

Group 3: Physical Acoustics

PAT Acoustic Tweezers and Particle Manipulation

PNL Nonlinear Acoustics

PGP General Physical Acoustics

PTE High Performance and Temperature Effects

POA Opto-acoustics

PPN Phononics

PTF Thin Films

PMI Modeling and Inversion

PUM Ultrasonic Motors & Actuators

PNR Non-Reciprocal Acoustics

Group 4: Microacoustics - SAW, FBAR, MEMS

ADA Device Applications

ADD Device Design

ADM Device Modeling

AMP Materials & Propagation

AMR Microacoustic Resonators

AMS Microacoustic Sensor Devices & Apps.

ATR Tunable & Reconfigurable Devices

Group 5: Transducers & Transducer Materials

TMC Materials Fabrication and Characterization

TMO Modeling (Analytical & Numerical)

TFT Thin and Thick Piezoelectric Films

TMU Micromachined Ultrasonic Transducers

TMI Biomedical Diagnostic and Imaging Transducers

TTT Biomedical Therapeutic Transducers

THF Front-end and Integrated Electronics

TFI High Frequency Transducers

TPF Applications of Piezoelectrics & Ferroelectrics

Student Travel Support: Limited funds are available to support IEEE UFFC student member attendees at the 2018 symposium. Awards will be given on a competitive basis. Please see the conference website for details.

Student Paper Competition: Students submitting abstracts are invited to participate in a student paper competition. To participate, the student must be the lead author and present his/her paper. Further information will be posted on the conference website.

Visa Application: Please visit the Symposium web site for updated information regarding invitation letters, and apply in advance if you need a visa to travel to Japan. The information is expected to be available in February 2018.